



October 2014

H11N1M, H11N2M, H11N3M — 6-Pin DIP Schmitt Trigger Output Optocoupler

# H11N1M, H11N2M, H11N3M 6-Pin DIP Schmitt Trigger Output Optocoupler

## Features

- High Data Rate, 5 MHz Typical (NRZ)
- Free from Latch-up and Oscillation Throughout Voltage and Temperature Ranges
- Microprocessor Compatible Drive
- Logic Compatible Output Sinks 16 mA at 0.5 V Maximum
- Guaranteed On/Off Threshold Hysteresis
- Wide Supply Voltage Capability, Compatible with All Popular Logic Systems
- Safety and Regulatory Approvals:
  - UL1577, 4,170 VAC<sub>RMS</sub> for 1 Minute
  - DIN-EN/IEC60747-5-5, 850 V Peak Working Insulation Voltage

## Description

The H11NXM series has a high-speed integrated circuit detector optically coupled to an aluminium gallium arsenide (AlGaAs) infrared emitting diode. The output incorporates a Schmitt trigger, which provides hysteresis for noise immunity and pulse shaping. The detector circuit is optimized for simplicity of operation and utilizes an open-collector output for maximum application flexibility.

## Applications

- Logic-to-Logic Isolator
- Programmable Current Level Sensor
- Line Receiver—Eliminate Noise and Transient Problems
- AC to TTL Conversion—Square Wave Shaping
- Interfaces Computers with Peripherals
- Isolated Power MOS Driver for Power Supplies

## Schematic

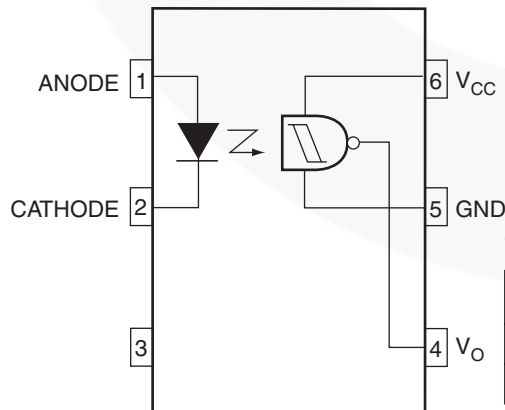


Figure 1. Schematic

### Truth Table

Input	Output
H	L
L	H

## Package Outlines

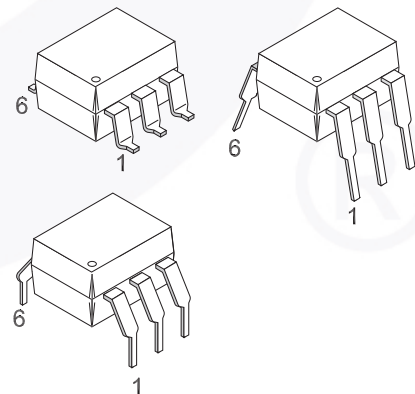


Figure 2. Package Outlines

## Safety and Insulation Ratings

As per DIN EN/IEC 60747-5-5, this optocoupler is suitable for “safe electrical insulation” only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Parameter		Characteristics
Installation Classifications per DIN VDE 0110/1.89 Table 1, For Rated Mains Voltage	< 150 V <sub>RMS</sub>	I–IV
	< 300 V <sub>RMS</sub>	I–IV
Climatic Classification		55/100/21
Pollution Degree (DIN VDE 0110/1.89)		2
Comparative Tracking Index		175

Symbol	Parameter	Value	Unit
V <sub>PR</sub>	Input-to-Output Test Voltage, Method A, V <sub>IORM</sub> × 1.6 = V <sub>PR</sub> , Type and Sample Test with t <sub>m</sub> = 10 s, Partial Discharge < 5 pC	1360	V <sub>peak</sub>
	Input-to-Output Test Voltage, Method B, V <sub>IORM</sub> × 1.875 = V <sub>PR</sub> , 100% Production Test with t <sub>m</sub> = 1 s, Partial Discharge < 5 pC	1594	V <sub>peak</sub>
V <sub>IORM</sub>	Maximum Working Insulation Voltage	850	V <sub>peak</sub>
V <sub>IOTM</sub>	Highest Allowable Over-Voltage	6000	V <sub>peak</sub>
	External Creepage	≥ 7	mm
	External Clearance	≥ 7	mm
	External Clearance (for Option TV, 0.4" Lead Spacing)	≥ 10	mm
DTI	Distance Through Insulation (Insulation Thickness)	≥ 0.5	mm
T <sub>S</sub>	Case Temperature <sup>(1)</sup>	175	°C
I <sub>S,INPUT</sub>	Input Current <sup>(1)</sup>	350	mA
P <sub>S,OUTPUT</sub>	Output Power <sup>(1)</sup>	800	mW
R <sub>IO</sub>	Insulation Resistance at T <sub>S</sub> , V <sub>IO</sub> = 500 V <sup>(1)</sup>	> 10 <sup>9</sup>	Ω

**Note:**

1. Safety limit values – maximum values allowed in the event of a failure.

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.  $T_A = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameters	Value	Units
<b>Total Device</b>			
$T_{\text{STG}}$	Storage Temperature	-40 to +125	$^\circ\text{C}$
$T_{\text{OPR}}$	Operating Temperature	-40 to +85	$^\circ\text{C}$
$T_J$	Junction Temperature	-40 to +125	$^\circ\text{C}$
$T_{\text{SOL}}$	Lead Solder Temperature	260 for 10 seconds	$^\circ\text{C}$
$P_D$	Total Device Power Dissipation at $25^\circ\text{C}$	210	mW
	Derate Above $25^\circ\text{C}$	2.94	mW/ $^\circ\text{C}$
<b>Emitter</b>			
$I_F$	Continuous Forward Current	30	mA
$V_R$	Reverse Voltage	6	V
$I_F(\text{pk})$	Forward Current – Peak (1 $\mu\text{s}$ pulse, 300 pps)	100	mA
$P_D$	LED Power Dissipation	60	mW
<b>Detector</b>			
$P_D$	Detector Power Dissipation	150	mW
$V_O$	$V_{45}$ Allowed Range	0 to 16	V
$V_{\text{CC}}$	$V_{65}$ Allowed Range	3 to 16	V
$I_O$	$I_4$ Output Current	50	mA

## Electrical Characteristics

$T_A = 25^\circ\text{C}$  unless otherwise specified.

### Individual Component Characteristics

Symbol	Parameters	Test Conditions	Device	Min.	Typ.	Max.	Units
<b>Emitter</b>							
$V_F$	Input Forward Voltage	$I_F = 10\text{ mA}$	All		1.4	2.0	V
		$I_F = 0.3\text{ mA}$		0.75	1.25		
$I_R$	Reverse Current	$V_R = 5\text{ V}$	All			10	$\mu\text{A}$
$C_J$	Capacitance	$V = 0, f = 1.0\text{ MHz}$	All			100	pF
<b>Detector</b>							
$V_{\text{CC}}$	Operating Voltage Range		All	4		15	V
$I_{\text{CC(off)}}$	Supply Current	$I_F = 0, V_{\text{CC}} = 5\text{ V}$	All		6	10	mA
$I_{\text{OH}}$	Output Current, High	$I_F = 0, V_{\text{CC}} = V_O = 15\text{ V}$	All			100	$\mu\text{A}$

**Electrical Characteristics** (Continued)T<sub>A</sub> = 25°C unless otherwise specified.**Transfer Characteristics**

Symbol	DC Characteristics	Test Conditions	Device	Min.	Typ.	Max.	Units
I <sub>CC(on)</sub>	Supply Current	I <sub>F</sub> = 10 mA, V <sub>CC</sub> = 5 V	All		6.5	10.0	mA
V <sub>OL</sub>	Output Voltage, Low	R <sub>L</sub> = 270 Ω, V <sub>CC</sub> = 5 V, I <sub>F</sub> = I <sub>F(on)</sub> Maximum	All			0.5	V
I <sub>F(on)</sub>	Turn-On Threshold Current	R <sub>L</sub> = 270 Ω, V <sub>CC</sub> = 5 V <sup>(2)</sup>	H11N1M	0.8		3.2	mA
			H11N2M	2.3		5.0	
			H11N3M	4.1		10.0	
I <sub>F(off)</sub>	Turn-Off Threshold Current	R <sub>L</sub> = 270 Ω, V <sub>CC</sub> = 5 V	All	0.3			mA
I <sub>F(off)</sub> / I <sub>F(on)</sub>	Hysteresis Ratio	R <sub>L</sub> = 270 Ω, V <sub>CC</sub> = 5 V	All	0.65		0.95	

**Switching Speed**

Symbol	AC Characteristics	Test Conditions	Device	Min.	Typ.	Max.	Units
t <sub>on</sub>	Turn-On Time	C = 120 pF, t <sub>p</sub> = 1 μs, R <sub>E</sub> = <sup>(3)</sup> , Figure 9	All		100	330	ns
t <sub>r</sub>	Rise Time	C = 120 pF, t <sub>p</sub> = 1 μs, R <sub>E</sub> = <sup>(3)</sup> , Figure 9	All		7.5		ns
t <sub>off</sub>	Turn-Off Time	C = 120 pF, t <sub>p</sub> = 1 μs, R <sub>E</sub> = <sup>(3)</sup> , Figure 9	All		150	330	ns
t <sub>f</sub>	Fall Time	C = 120 pF, t <sub>p</sub> = 1 μs, R <sub>E</sub> = <sup>(3)</sup> , Figure 9	All		12		ns
	Data Rate		All		5		MHz

**Isolation Characteristics**

Symbol	Parameters	Test Conditions	Min.	Typ.	Max.	Units
V <sub>ISO</sub>	Input-Output Isolation Voltage	t = 1 Minute	4170			V <sub>ACRMS</sub>
C <sub>ISO</sub>	Isolation Capacitance	V <sub>I-O</sub> = 0 V, f = 1 MHz		0.4	0.6	pF
R <sub>ISO</sub>	Isolation Resistance	V <sub>I-O</sub> = ±500 VDC, T <sub>A</sub> = 25°C	10 <sup>11</sup>			Ω

**Notes:**

- Maximum I<sub>F(on)</sub> is the maximum current required to trigger the output. For example, a 3.2 mA maximum trigger current would require the LED to be driven at a current greater than 3.2 mA to guarantee the device will turn on. A 10% guard band is recommended to account for degradation of the LED over its lifetime. The maximum allowable LED drive current is 30 mA.
- H11N1: R<sub>E</sub> = 910 Ω, H11N2: R<sub>E</sub> = 560 Ω, H11N3: R<sub>E</sub> = 240 Ω

Typical Performance Curves

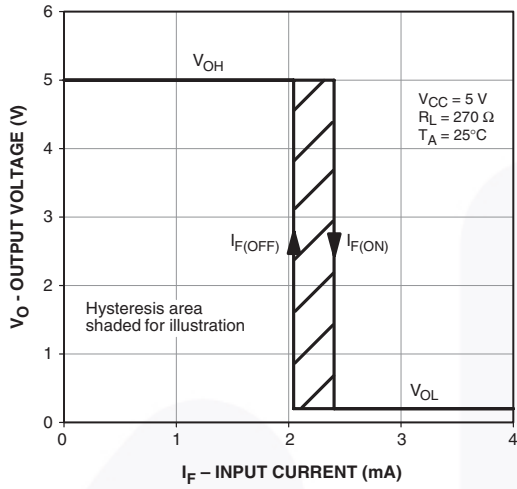


Figure 3. Transfer Characteristics

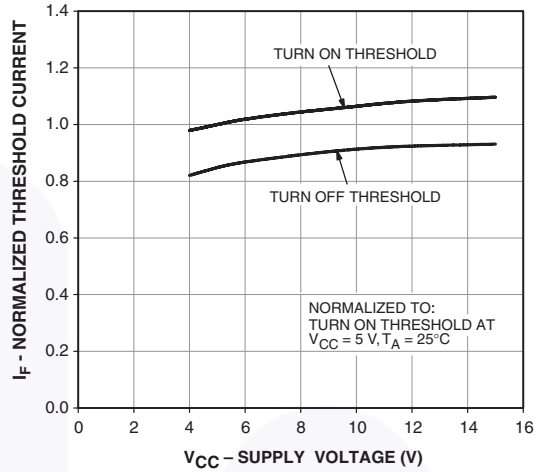


Figure 4. Threshold Current vs. Supply Voltage

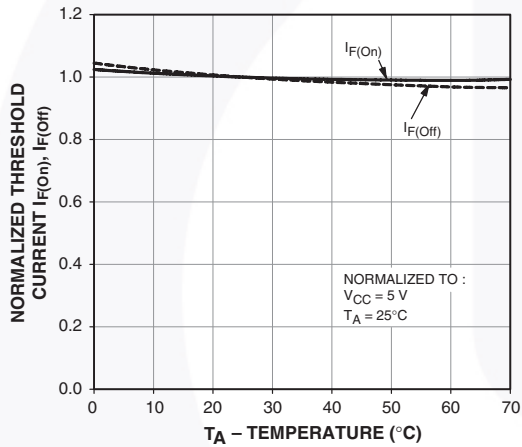


Figure 5. Threshold Current vs. Temperature

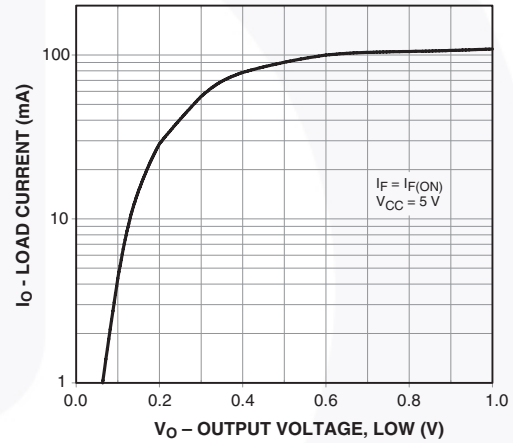


Figure 6. Load Current vs. Output Voltage

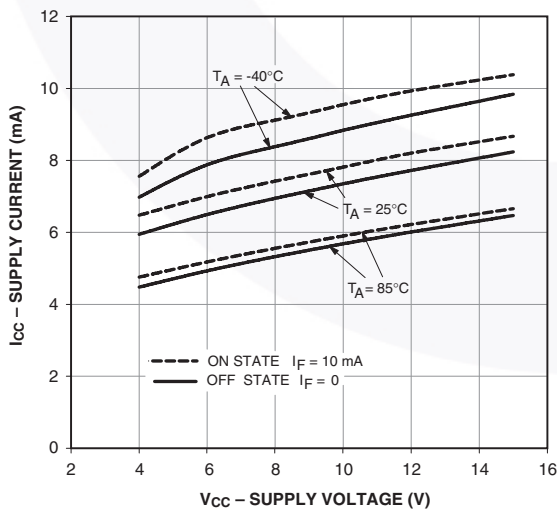


Figure 7. Supply Current vs. Supply Voltage

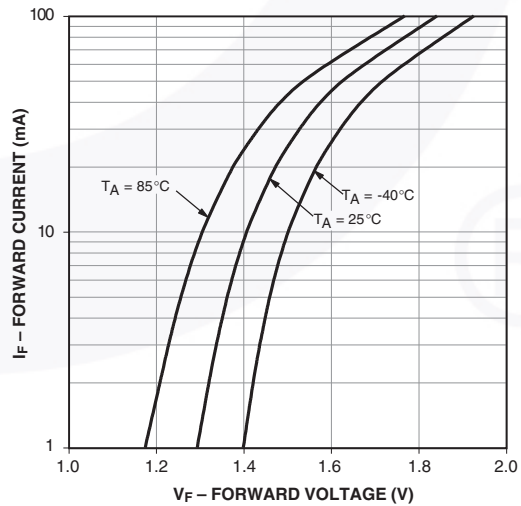


Figure 8. LED Forward Current vs. Forward Voltage

### Switching Test Circuit and Waveforms

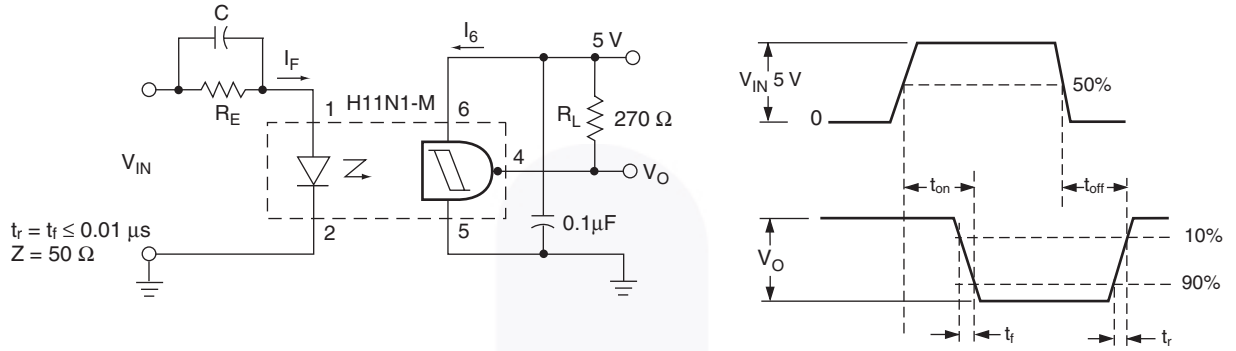


Figure 9. Switching Test Circuit and Waveforms

### Reflow Profile

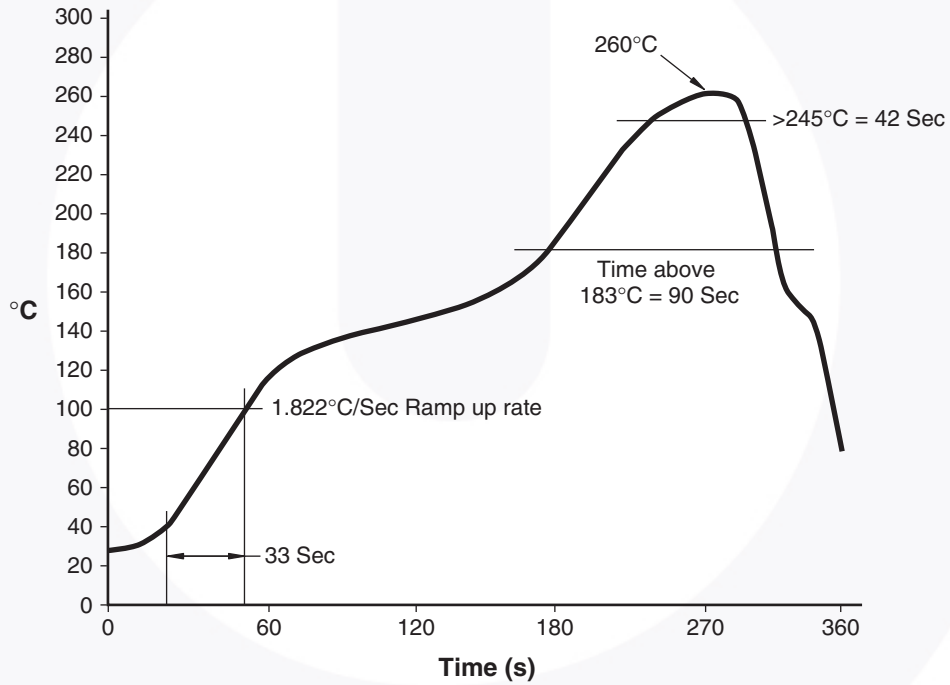


Figure 10. Reflow Profile

## Ordering Information

Part Number	Package	Packing Method
H11N1M	DIP 6-Pin	Tube (50 Units)
H11N1SM	SMT 6-Pin (Lead Bend)	Tube (50 Units)
H11N1SR2M	SMT 6-Pin (Lead Bend)	Tape and Reel (1000 Units)
H11N1VM	DIP 6-Pin, DIN EN/IEC60747-5-5 Option	Tube (50 Units)
H11N1SVM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	Tube (50 Units)
H11N1SR2VM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	Tape and Reel (1000 Units)
H11N1TVM	DIP 6-Pin, 0.4" Lead Spacing, DIN EN/IEC60747-5-5 Option	Tube (50 Units)

**Note:**

4. The product orderable part number system listed in this table also applies to the H11N2M and H11N3M product families.

## Marking Information

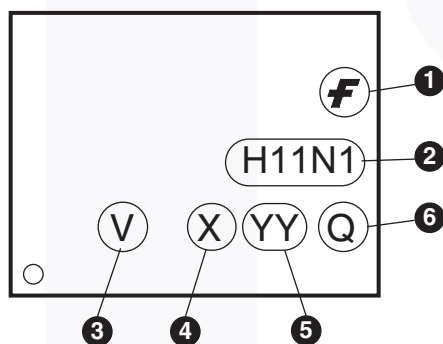
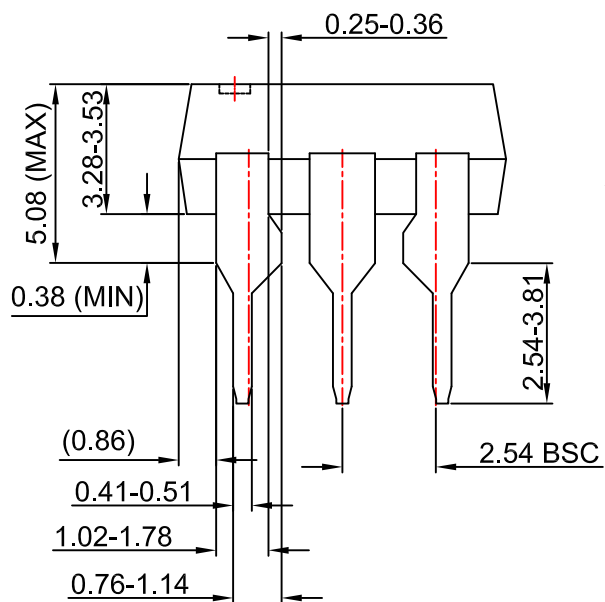
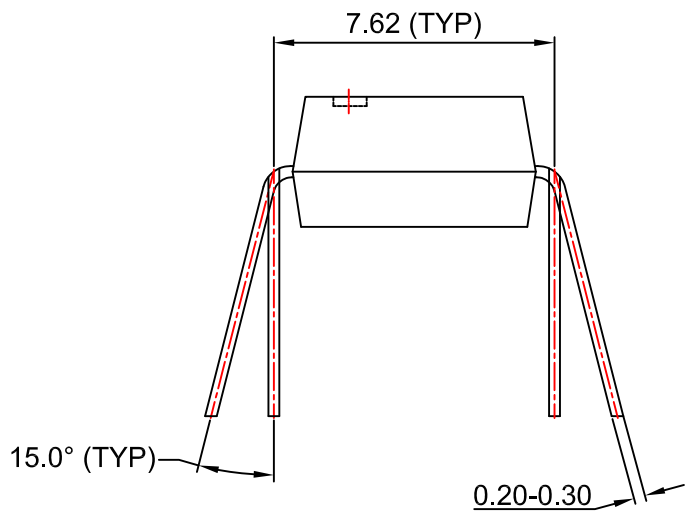
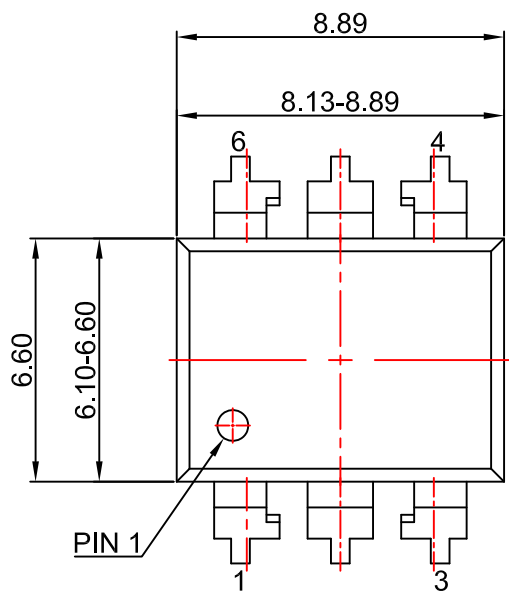


Figure 11. Top Mark

Table 1. Top Mark Definitions

1	Fairchild Logo
2	Device Number
3	DIN EN/IEC60747-5-5 Option (only appears on component ordered with this option)
4	One-Digit Year Code, e.g., "4"
5	Digit Work Week, Ranging from "01" to "53"
6	Assembly Package Code

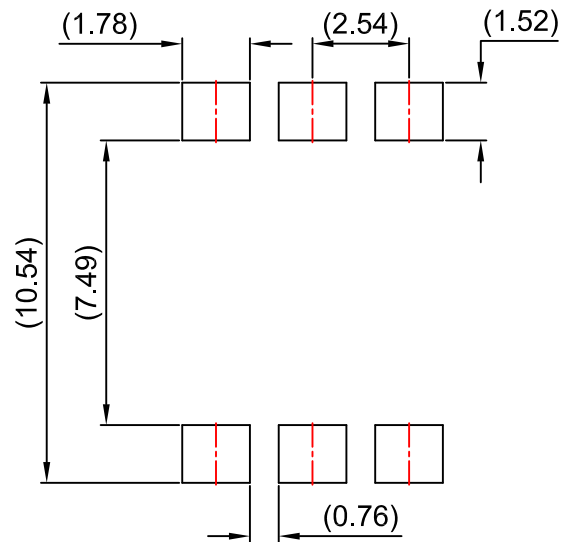
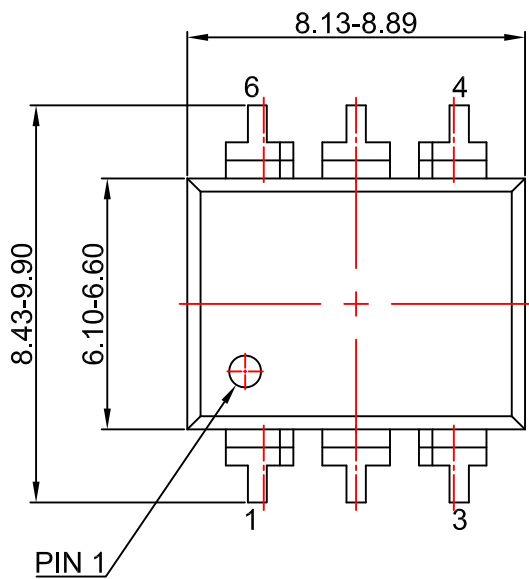


NOTES:

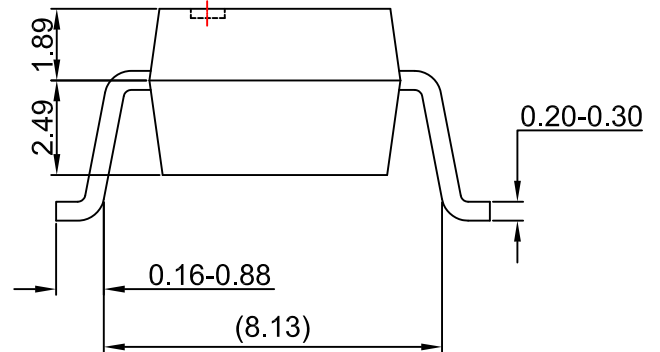
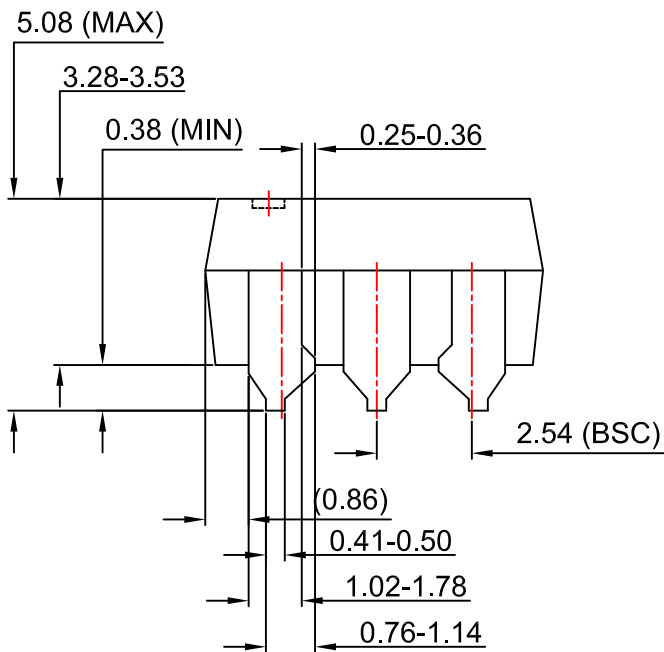
- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVISION: MKT-N06BREV4.







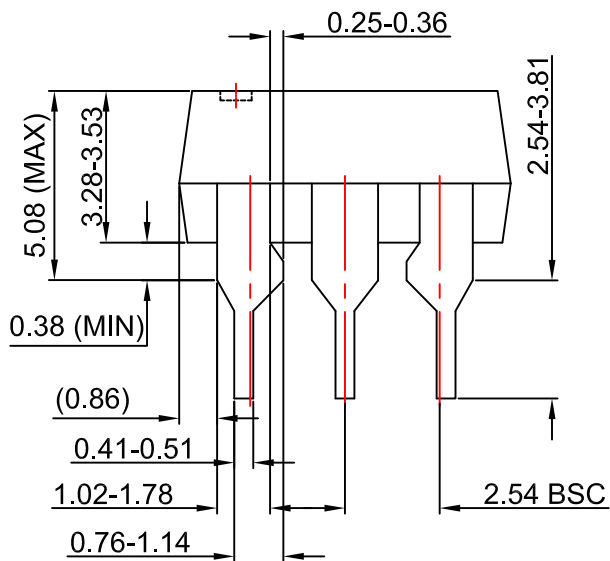
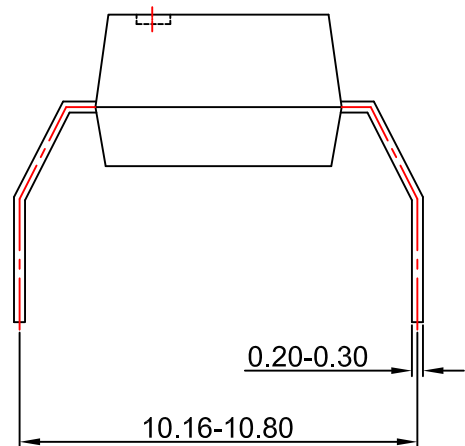
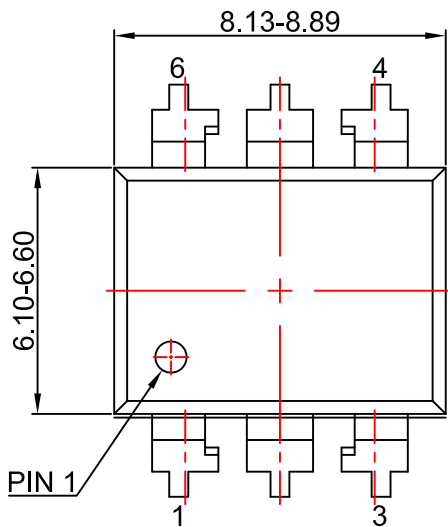
LAND PATTERN RECOMMENDATION



NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVISION : MKT-N06CREV4.





NOTES:






- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVISION: MKT-N06Drev4





**TRADEMARKS**

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

- |   |  |   |   |
|---|--|---|---|
| AccuPower™  | F-PFS™   | OPTOPLANAR®   |  |
| AttitudeEngine™   | FRFET®   |  | TinyBoost®  |
| Awinda®   | Global Power Resource <sup>SM</sup>            | PowerTrench®  | TinyBuck®   |
| AX-CAP®*  | GreenBridge™                                   | PowerXS™  | TinyCalc™   |
| BitSiC™   | Green FPS™                                     | Programmable Active Droop™  | TinyLogic®  |
| Build it Now™   | Green FPS™ e-Series™                           | QFET®   | TINYOPTO™   |
| CorePLUS™   | Gmax™  | QS™   | TinyPower™  |
| CorePOWER™  | GTO™   | Quiet Series™   | TinyPWM™  |
| CROSSVOLT™  | IntelliMAX™                                    | RapidConfigure™   | TinyWire™   |
| CTL™  | ISOPLANAR™                                     |  | TranSiC™  |
| Current Transfer Logic™   | Making Small Speakers Sound Louder and Better™ | Saving our world, 1mW/W/kW at a time™   | TriFault Detect™  |
| DEUXPEED®   | MegaBuck™                                      | SignalWise™   | TRUECURRENT®*   |
| Dual Cool™  | MICROCOUPLER™                                  | SmartMax™   | μSerDes™  |
| EcoSPARK®   | MicroFET™                                      | SMART START™  |  |
| EfficientMax™   | MicroPak™                                      | Solutions for Your Success™   | UHC®  |
| ESBC™   | MicroPak2™                                     | SPM®  | Ultra FRFET™  |
|  | MillerDrive™                                   | STEALTH™  | UniFET™   |
| Fairchild®  | MotionMax™                                     | SuperFET®   | Vcx™  |
| Fairchild Semiconductor®  | MotionGrid®                                    | SuperSOT™-3   | VisualMax™  |
| FACT Quiet Series™  | MTI®   | SuperSOT™-6   | VoltagePlus™  |
| FACT®   | MTX®   | SuperSOT™-8   | XS™   |
| FAST®   | MVN®   | SupreMOS®   | Xsens™  |
| FastvCore™  | mWSaver®                                       | SyncFET™  | 仙童™   |
| FETBench™   | OptoHiT™                                       | Sync-Lock™  |   |
| FPS™  | OPTOLOGIC®                                     |   |   |

\* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

**DISCLAIMER**

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR WEBSITE AT [HTTP://WWW.FAIRCHILDSEMI.COM](http://www.fairchildsemi.com). FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

**LIFE SUPPORT POLICY**

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

**ANTI-COUNTERFEITING POLICY**

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, [www.fairchildsemi.com](http://www.fairchildsemi.com), under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

**PRODUCT STATUS DEFINITIONS**

**Definition of Terms**

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.